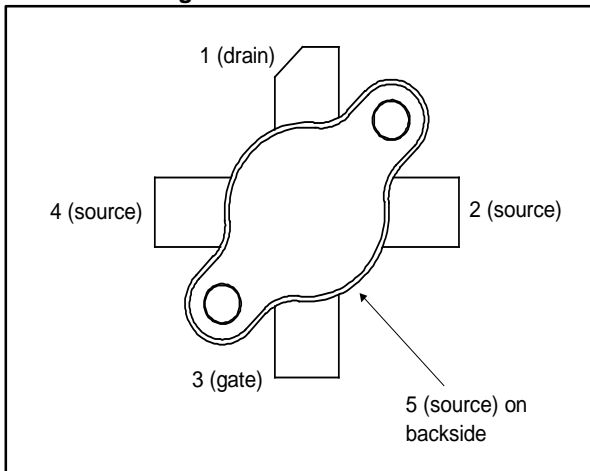


**Figure 1: Pin connection**



### Description

The STAC250V2-500E uses the latest RF Power SuperDMOS technology specially designed for 150 V and 250 V industrial RF power Class-C, D and E generators such as PECVD, plasma sputtering, flat panel and solar cell manufacturing equipment. The STAC250V2-500E benefits from the latest generation of STAC® air cavity packaging, which exhibits a 25% lower thermal resistance compared to equivalent ceramic packages.

**Table 1: Device summary**

Order code	Marking	Package	Packaging
STAC250V2-500E	250V2-500 <sup>(1)</sup>	STAC177B	Plastic tray

#### Notes:

<sup>(1)</sup>For more details please refer to [Section 6: "Marking, packing and shipping specifications"](#).

### Features

- Operating frequency up to 27 MHz
- $P_{OUT} = 450 \text{ W}$  with 23 dB gain @ 13.56 MHz/250 V
- Designed for Class-C, D and E operation
- $V_{(BR)DSS} > 900 \text{ V}$
- Housed in STAC® package, using air cavity packaging technology
- In compliance with the 2002/95/EC1 European Directive

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# 1 Electrical data

## 1.1 Maximum ratings

( $T_{CASE} = 25\text{ °C}$ )

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-source voltage	900	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$T_J$	Max. operating junction temperature	200	°C
$T_{STG}$	Storage temperature	-65 to +150	°C

## 1.2 Thermal data

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thJC}$	Junction-case thermal resistance	TBD	°C/W

## 2 Electrical characteristics

$T_{CASE} = +25\text{ }^{\circ}\text{C}$

### 2.1 Static

Table 4: Static

Symbol	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	$I_{DS} = 250\text{ }\mu\text{A}$	900			V
$I_{DSS}$	$V_{GS} = 0\text{ V}; V_{DS} = 750\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	$V_{GS} = 20\text{ V}; V_{DS} = 0\text{ V}$			1	$\mu\text{A}$
$V_{TH}$	$I_D = 250\text{ }\mu\text{A}$	3	4.7	6	V
$V_{DS(ON)}$	$V_{GS} = 10\text{ V}; I_D = 7\text{ A}$		4.2	5	V
$G_{FS}$	$V_{DS} = 7\text{ V}; I_D = 3.5\text{ A}$		4.4		S
$C_{ISS}$	$V_{GS} = 0\text{ V}; V_{DS} = 150\text{ V}; f = 1\text{ MHz}$		980		pF
$C_{OSS}$	$V_{GS} = 0\text{ V}; V_{DS} = 150\text{ V}; f = 1\text{ MHz}$		140		pF
$C_{RSS}$	$V_{GS} = 0\text{ V}; V_{DS} = 150\text{ V}; f = 1\text{ MHz}$		1		pF

### 2.2 Dynamic

Frequency = 13.56 MHz Class-C

Table 5: Dynamic

Symbol	Test conditions	Min.	Typ.	Max.	Unit
$P_{OUT}$	$V_{DD} = 150\text{ V}, P_{IN} = 3.5\text{ W}$	450	500	-	W
	$V_{DD} = 250\text{ V}, P_{IN} = 2.5\text{ W}$	450	600	-	
Gain	$V_{DD} = 150\text{ V}, P_{IN} = 3.5\text{ W}$		21.5	-	dB
	$V_{DD} = 250\text{ V}, P_{IN} = 2.5\text{ W}$		23.5	-	
Efficiency	$V_{DD} = 150\text{ V}, P_{OUT} = 3.5\text{ W}$	70	78	-	%
	$V_{DD} = 250\text{ V}, P_{OUT} = 2.5\text{ W}$		75	-	%
Load mismatch	$V_{DD} = 150\text{ V}, P_{OUT} = 450\text{ W}$		10:1 <sup>(1)</sup> 65:1	-	VSWR
	$V_{DD} = 250\text{ V}, P_{OUT} = 450\text{ W}$		3:1 20:1 <sup>(1)</sup>	-	

**Notes:**

<sup>(1)</sup>Under pulse conditions: 1 ms - 10%.

### 3 Impedance data

Figure 2: Impedance data

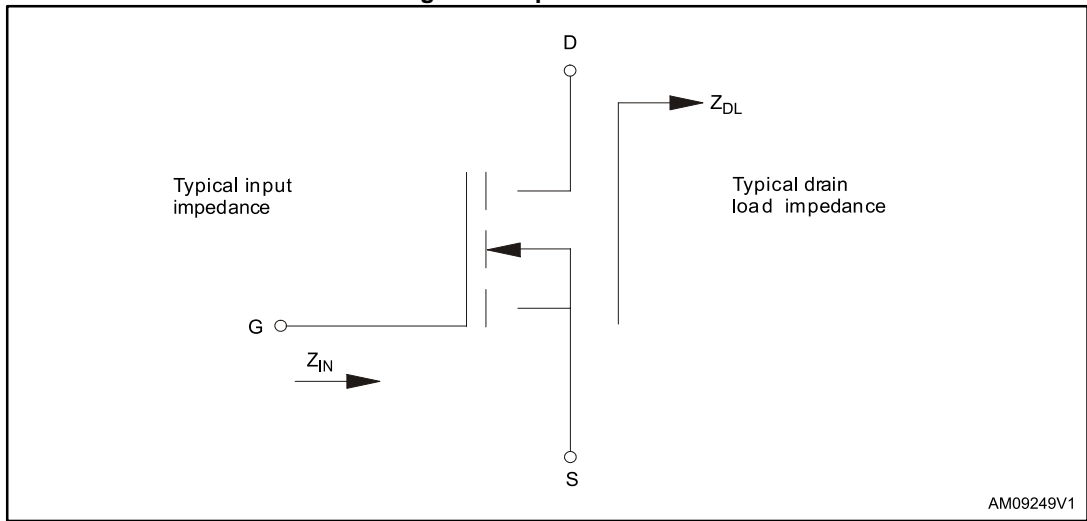


Table 6: Impedance values

Frequency (MHz)	Z <sub>in</sub>	Z <sub>dl</sub>
13.56	TBD	TBD

## 4 Typical performance

Figure 3: Capacitance vs. drain-source voltage

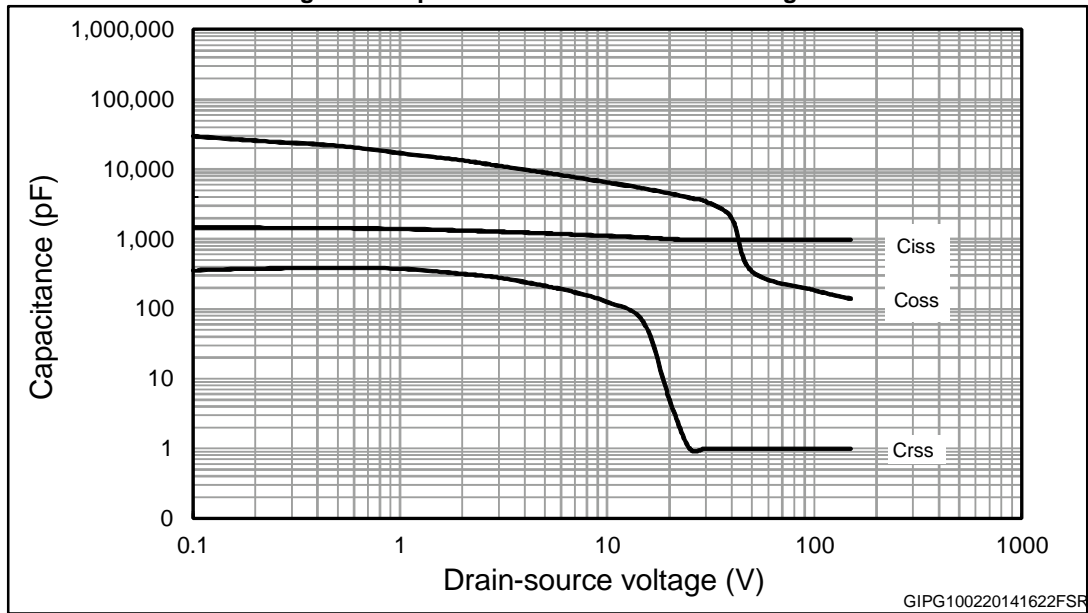


Figure 4: Gain and efficiency vs. output power @ 150 V

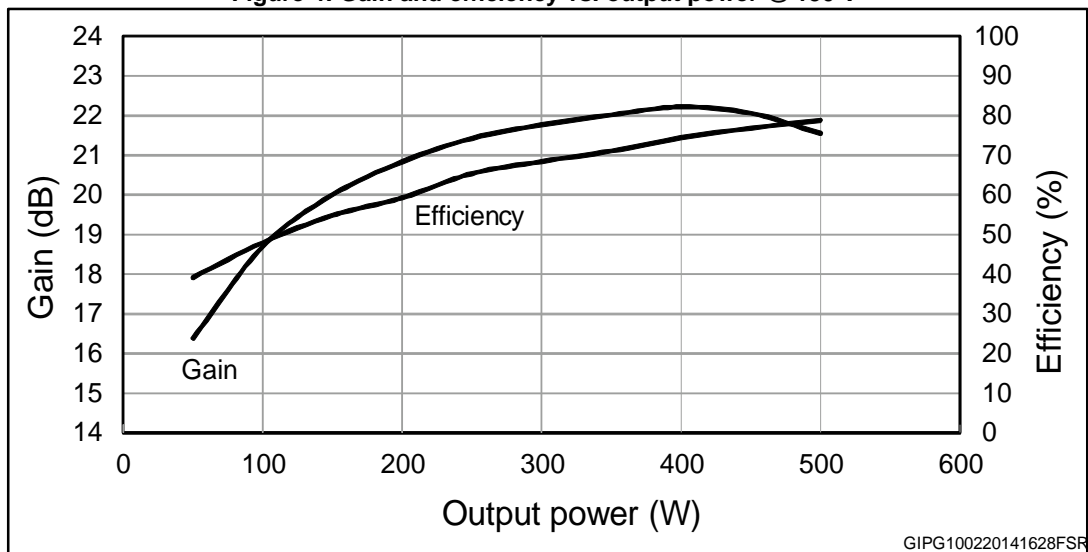
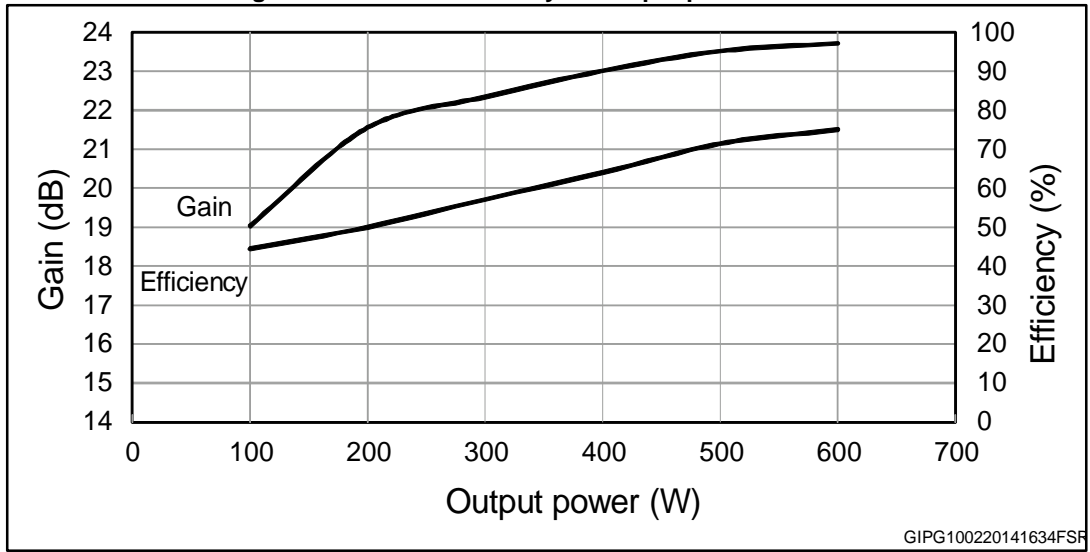


Figure 5: Gain and efficiency vs. output power @ 250 V



## 5 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 5.1 STAC177B mechanical data

Figure 6: STAC177B mechanical drawings

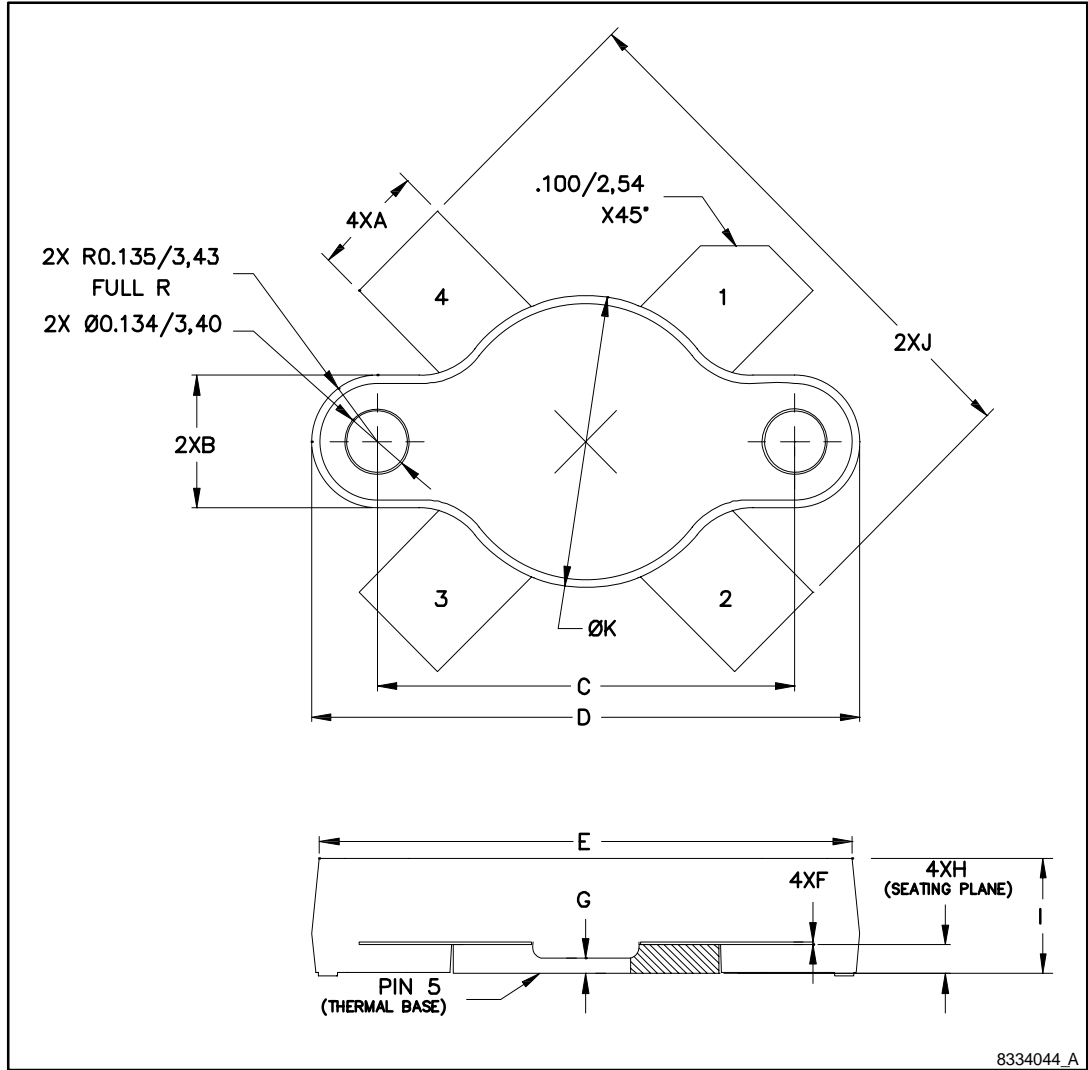




Table 7: STAC177B mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	5.72		5.97
B	6.73		6.99
C	21.84		22.10
D	28.70		28.96
E		28.02	
F	0.10		0.15
G		0.81	
H	1.45		1.70
I	5.79		6.15
J	27.43		28.45
K	15.01		15.27

## 6 Marking, packing and shipping specifications

Table 8: Packing and shipping specifications

Order code	Packaging	Pieces per tray	Dry pack humidity	Lot code
STAC250V2-500E	Plastic tray	25	< 10%	Not mixed

Figure 7: Marking layout

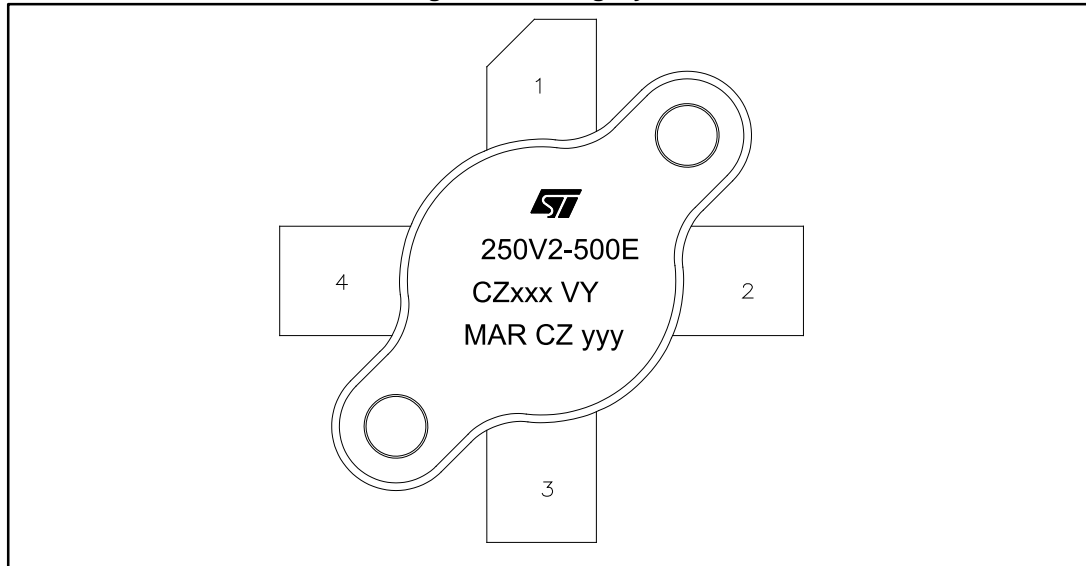


Table 9: Marking specifications

Symbol	Description
CZ	Assembly plant
xxx	Last 3 digits of diffusion lot
VY	Diffusion plant
MAR	Country of origin
CZ	Test and finishing plant
y	Assembly year
yy	Assembly week

## 7 Revision history

Table 10: Document revision history

Date	Revision	Changes
14-Mar-2014	1	Initial release.
04-Aug-2014	2	Modified title in cover page. Updated <a href="#">Table 4: "Static"</a> Minor text change
15-Sep-2014	3	Document status promoted from preliminary to production data.

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